Name	ok525ome.zip	Id.	33383 - QED OK
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Single PCB View - Original

Top View	Bottom View

Summary - General - Original

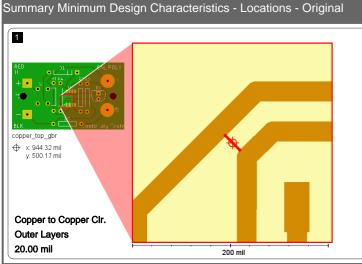|			
PCB Size	1.9685 inch x 1.1811 inch	Surface Finish	unknown
PCB Thickness	62.00 mil	Max. Aspect Ratio on PTH	2.0
Customer Panel Size		Number of Nets	12
Copper Layers	2	Electrical Test	Single Sided
Solder Mask	Both	Drilled SMD Pads	No
Solder Mask Color	Green	SMD Pads Top	8
Legend	Top Only	SMD Pads Bottom	0
Legend Color	White	BGA Pads Top	0
Peeloff Mask	None	BGA Pads Bottom	0
Carbon Mask	None	Drill Hole Density	10 Holes/inch^2
Edge Connectors	No		

Summary - Copper Layers - Original

Layer Type	Min. Copper Width	Min. Critical Copper Width	Min. Trace Width	Min. Critical Trace Width	Min. Clr. Copper to Copper	Min. Clr. Trace to Trace	Min. Same Net Spacing	Min. Ring	Copper to Plated Clr.	Copper to NPTH Clr.	Copper to Outline Clr.
	mil	mil	mil	mil	mil	mil	mil	mil	mil	mil	mil
Outer	>16.00	>16.00	>16.00	>16.00	[1] 20.00	[2] 20.00	>20.00	[3] 13.51	>32.00	[4] 45.61	>64.00

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Summary - Sequences - Original

Type	Sequences	Tools	Min. End Dia.	Max. End Dia.	Holes	Moves	Min. Ring on Outer	Min. Ring on Inner	Min. Clr. Hole to Copper
			mil	mil			mil	mil	mil
Blind	0								
Buried	0								
PTH	1	2	31.50	40.98	22	0	13.51		>32.00
Plated (Total)	1	2	31.50	40.98	22	0	13.51		>32.00
NPTH	1	1	125.00	125.00	2	0	>32.00		45.61
Total	2	3	31.50	125.00	24	0	13.51		45.61

Summary Minimum Design Characteristics - Locations - Original

1

copper_top_gbr

⊕ x: 944.32 mil
y: 500.17 mil

Copper to Copper Clr.
Outer Layers
20.00 mil

200 mil

2

copper_top_gbr

⊕ x: 944.32 mil
y: 500.17 mil

Min. Clr. Trace to Trace
Outer Layers
20.00 mil

200 mil

3

copper_top_gbr

⊕ x: 452.36 mil
y: 462.6 mil

Min. Ring
Outer Layers
13.51 mil

100 mil

4

copper_top_gbr

⊕ x: 1686.35 mil
y: 590.55 mil

Clr. to NPTH
Outer Layers
45.61 mil

500 mil

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Stackup - Original

copper_top_gbr

copper_bottom_gbr

Pressing Stages	1

Copper Layer Minima & Area - Original

File	Pos.	Min. Copper Width	Min. Critical Copper Width	Min. Trace Width	Min. Critical Trace Width	Min. Clr. Copper to Copper	Min. Clr. Trace to Trace	Min. Same Net Spacing	Min. Ring	Copper to Plated Clr.	Copper to NPTH Clr.	Copper to Outline Clr.	Copper Area	
		mil	mil	mil	mil	mil	mil	mil	mil	mil	mil	mil	inch^2	%
copper_top_gbr	1	>16.00	>16.00	>16.00	>16.00	20.00	20.00	>20.00	13.51	>32.00	45.61	>64.00	0.3681	16
copper_bottom_gbr	2	>16.00	>16.00	>16.00	>16.00	>32.00	>20.00	>20.00	13.51	>32.00	>64.00	>64.00	0.2033	9

Drill Tools - Original

File	Tool Nr.	Span	Type	Method	FilledVia	Countered	Dia.	Tol. Min	Tol. Plus	Holes (in PCB)	Moves (in PCB)	Double Hits (in File)	Predrill Hits (in File)	Min. Ring on Outer	Min. Ring on Inner	Min. Pad Size
							mil	mil	mil					mil	mil	mil
drills_xln	1	1-2	NPTH	unknown	unknown	unknown	125.00	0.00	0.00	2	0	0	0	>32.00		
drills_xln	2	1-2	PTH	unknown	unknown	unknown	40.98	0.00	0.00	8	0	0	0	13.51		68.00
drills_xln	3	1-2	PTH	unknown	unknown	unknown	31.50	0.00	0.00	14	0	0	0	17.72		66.94

Sequences - Original

Span	Type	Tools	Min. End Dia.	Max. End Dia.	Holes	Min. Ring on Outer	Min. Ring on Inner	Min. Clr. Hole to Copper	Min. Clr. Hole to Outline	Min. Clr. Slot to Outline
			mil	mil		mil	mil	mil	mil	mil
1-2	PTH	2	31.50	40.98	22	13.51		>32.00	88.19	disabled
All	Plated	2	31.50	40.98	22	13.51		>64.00	88.19	disabled
1-2	NPTH	1	125.00	125.00	2	>32.00		45.61	134.35	disabled
All	All	3	31.50	125.00	24	13.51		45.61	88.19	disabled

Rout Tools - Original

File	Tool Nr.	Type	Tool Dia.	End Dia.	Draw Length	Nibble Count
			mil	mil	mil	

Routed Holes - Original

File	Hole Nr.	Instances	X Size	Y Size	Draw Length	Nibble Count
			mil	mil	mil	

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Solder Mask - Original

Side	Min. Ring on Cu Defined Pads	Min. Ring on SM Defined Pads	Min. Clr. Mask to Mask	Min. Web	Min. Clr. Mask to Copper	Fully Covered Via Holes	Partly Covered Via Holes	TH Via Holes Half Mask
	mil	mil	mil	mil	mil			
Top	4.00	>10.00	>10.00	>10.00	>10.00	No	No	
Bottom	4.00	>10.00	>10.00	>10.00	>10.00	No	No	
Both	4.00	>10.00	>10.00	>10.00	>10.00	No	No	No

Files - Original

Initial	Renamed	Format	Function	Position	Color
solderpaste_top.gbr	solderpaste_top_gbr	ger274x	paste	top	
silkscreen_top.gbr	silkscreen_top_gbr	ger274x	silk	top	white
soldermask_top.gbr	soldermask_top_gbr	ger274x	mask	top	green
copper_top.gbr	copper_top_gbr	ger274x	outer	1	
copper_bottom.gbr	copper_bottom_gbr	ger274x	outer	2	
soldermask_bottom.gbr	soldermask_bottom_gbr	ger274x	mask	bottom	green
drills.xln	drills_xln	excellon2	mixed	1-2	
profile.gbr	profile_gbr	ger274x	cad_outline	none	
gerber_job.gbrjob		text	document		

Comments - Original